Note from the Editor

Welcome to the December 2016 eNewsletter of the Journal of Electronic Packaging (JEP). The eNewsletter, issued quarterly, will keep you abreast of the latest research developments in our field. Below you will find a special issue with GE papers, an opportunity to publish papers in JEP by 2017, JEP awards, top five downloads, new review articles, InterPACK 2017 http://electronicpackaging.org, and reach-out to Web of Science. Thank you for taking the time to read this eNewsletter – and please don’t hesitate to provide feedback by emailing me at my address below.

Sincerely,

Y.C. Lee
Editor, Journal of Electronic Packaging
leeyc@colorado.edu

Special Issue – GE Global Research Invited Papers

We plan to publish a special issue or series of review articles written by professionals in leading companies. The first special issue will be published next September 2017, and will include outstanding invited GE Global Research papers of interest to the electronics and photonics packaging community. The papers will cover topic areas related to Microsystems for Industrial Internet of Things (IIoT), Harsh Environment Electronics, and Power Electronics Packaging.
The Guest Editor for the special issue is Dr. Kaustubh Nagarkar of GE Global Research.

**High Quality Papers to be Reviewed and Published in 2017!**

There is room for high quality papers to be reviewed and published in the upcoming JEP 2017 issues. We have established a system that will make sure the initial review of every paper submitted to the journal will be completed in 8 weeks, and excellent papers can be published this year. You are welcome to submit your manuscript.

**2016 JEP Awards**

**JEP Best Paper Award** – Benchmarking Study on the Thermal Management Landscape for Three-Dimensional ICs: from Back-Side to Volumetric Heat Removal, by Thomas Brunschwiler, Research Staff Member, Arvind Sridhar, Postdoctoral Researcher, Gerd Schlottig, Researcher (IBM Research, Zürich Area, Switzerland), Chin Lee Ong, (Senior Collaborator at EPFL, École Polytechnique Fédérale de Lausanne, Lausanne, Switzerland).

**JEP Associate Editor Award** – Eric Wong
Dr. Tse Eric Wong is a Senior Engineering Fellow at the Raytheon Company and is a recognized international leader in durability/reliability and manufacturability of electronic interconnects, packages, and assemblies. He has also organized and chaired many technical sessions and served as a paper reviewer/judge for various conferences since 1996. He has been a JEP Associate Editor since January 2014.

**JEP Reviewer Award** – Kaushik Mysore
Dr. Kaushik Mysore has been employed at Advanced Micro Devices as a Sr. Product Development Engineer since 2009 where he has cross-disciplinary responsibilities in both the packaging and thermal disciplines. He has a PhD in Mechanical Engineering from Purdue University with research in areas of computational mechanics, fracture and damage in brittle and ductile materials, viscoplastic material characterization and reliability as applied to electronic packaging. He has been a JEP Guest Editor since 2015.

**Top Five Downloads!**
The numbers of downloads of top JEP papers from January to October in 2016 have increased to a level that is about 3-10x higher than those of papers in 2015. The following five are top downloads:

**Stretchable Thin Film Materials: Fabrication, Application, and Mechanics** Yu Wang; Zhengwei Li; Jianliang Xiao, June 2016

**Nanothermal Interface Materials: Technology Review and Recent Results** Avram Bar-Cohen, Kaiser Matin and Sreekant Narumanchi, December 2015

**Overview and Outlook of Three-Dimensional Integrated Circuit Packaging** John H. Lau, December 2014

**Two-Phase Thermal Ground Planes: Technology Development and Parametric Results** Avram Bar-Cohen, Kaiser Matin, Nicholas Jankowski and Darin Sharar, March 2015

**A Brief Overview of Recent Developments in Thermal Management in Data Centers** Sami Alkharabsheh; John Fernandes; Betsegaw Gebrehiwot; Dereje Agonafer; Kanad Ghose; Alfonso Ortega; Yogendra Joshi; Bahgat Sammakia, December 2015

**JEP Review Articles!**

The following review article is published in the JEP and for a limited time this and other review articles are available for public access. The complete list of review articles is posted at [http://electronicpackaging.org](http://electronicpackaging.org).


**REVIEW ARTICLES COMING SOON:**

**Overview of Human Thermal Responses to Warm Surfaces of Electronic Devices**, Han Zhang, Alan Hedge (Cornell University), March 2017

**Moisture Ingress, Behavior and Prediction inside Semiconductor Packaging: A Review**, Bongtae Han, Dae-Suk Kim (University of Maryland), June 2017.

Click here to see the list of review articles published, to be published or to be submitted. Leaders in the field are invited to publish review articles on hot, emerging and fundamental topics. You are welcome to recommend topics and authors through our [LinkedIn site](http://electronicpackaging.org).
InterPACK 2017

The InterPACK ‘17 conference will be held from August 28, 2017 to September 1, 2017 at the Marriott Hotel, Santa Clara, CA. The conference web site and call for abstracts will be out in the near future. There were over 800 participants in InterPACK 2015. We expect to have a successful InterPACK in 2017. Mark your calendar.

Current JEP Issue (March 2017)

Click Here!

A New Companion Web Site: http://electronicpackaging.org

Electronic packaging integrates components into a microsystem or system; its design and manufacturing activities represent about 50% of all activities required to make a system hardware, e.g. a smartphone or data center. We have developed a companion web site (http://electronicpackaging.org) of the ASME Journal of Electronic Packaging (JEP), which serves as a bridge between researchers in academia and professionals in industry conducting R&D studies for system integration. From this web site you can get the latest information about the journal’s publications and free downloads of review articles on hot, emerging and fundamental topics. In addition, you will be able to access other information to enhance technical exchange. You are welcome to join our LinkedIn and interact with the JEP community.

Join Our Group!

Invitation to Thompson Reuters Web of Science distribution

We have broadened the access of our journal by inviting the Thomson Reuters Web of Science e-mail distribution list for free JEP review article downloads. The invitation reads: You are invited to download free copies of review articles published by ASME Journal of Electronic Packaging at http://electronicpackaging.org/. You will understand why a major US funding agency has invested over $100M to develop novel thermal management technologies illustrated by a thermal interface material as shown right. You will also know the 3D packaging technology as shown below, which is critical to manufacture USB memory sticks with capacity increased from 1GB to 64 GB or even 128 GB. ASME Journal of Electronic Packaging is committed to
establishing a bridge between the scientific research community and engineers conducting R&D for smaller, lower cost and more reliable Microsystems, including microelectronics, optoelectronics, microwave/RF, biomedical devices, sensors, actuators, micro-scaled energy systems, etc. It is a top journal covering frontier research studies in electronic packaging. In addition, leaders in the field are invited to publish review articles on hot, emerging, or fundamental topics.

Upcoming Events

IEEE iTherm
May 30–June 2, 2017
Orlando, FL

Journal of Electronic Packaging – Associate Editors

Mehmet Arik, PhD, Ozyegin University
Mehdi Asheghi, PhD, Stanford University
Satish Chaparala, PhD, Corning Inc.
Pradip Dutta, PhD, Indian Institute of Science
Ashish Gupta, PhD, Intel Corp.
Toru Ikeda, PhD, Kagoshima University
Yi-Shao Lai, PhD, Advanced Semiconductor Engineering (ASE), Inc.
Shi-Wei Ricky Lee, PhD, The Hong Kong University of Science and Technology
Xiaobing Luo, PhD, Huazhong University of Science & Technology
Seungbae (SB) Park, PhD, State University of New York at Binghamton
Jeffrey C. Suhling, PhD, Auburn University
Tse Eric Wong, PhD, Raytheon Company

Journal of Electronic Packaging – Guest Editors

Baris Dogruoz, PhD, Cisco Corp
Justin Weibel, PhD, Purdue University
Kaushik Mysore, PhD, AMD Corp
Ravi Annapragada, PhD, UTRC (United Technologies Research Center)
Kaustubh Nagarkar, PhD, GE Global Research

About the Journal of Electronic Packaging
Editor, Y. C. Lee,
University of Colorado Boulder
JEP Home Page, Editorial Board

The *Journal of Electronic Packaging* publishes papers that address 1) thermal management, applied mechanics and technologies for microsystems packaging; 2) critical issues in systems integration; 3) emerging packaging technologies and materials with micro/nano structures; and 4) general small scale systems. The journal is to serve researchers and engineers working in academic and industrial settings. Originality, scientific merit and high engineering relevance are the major criteria for the acceptance of a submitted paper. In addition, leaders in the field are invited to publish review articles on hot, emerging and fundamental topics. Send an email to leeyc@colorado.edu for any feedback or comments.

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